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Business Excellence is at the Core of ASMPT
The World’s Technology & Market Leader

Q3 2019 Group Revenue: USD 531m
(CAGR 2009 – Q3 2019 LTM 13.1%)
ASMPT Global Presence

>2,000 Global R&D staff

>1,400 Patents on key leading edge technologies

10 R&D centres worldwide

12 Manufacturing facilities

OVERVIEW

Sales Offices

Business Centre / R&D / Manufacturing Site
ASMPT’S Major Facilities Around The World
Three Business Segments With Leading Market Positions

**BACK-END EQUIPMENT**

- **#1** in Assembly & Packaging Equipment Market
  
  *Since 2002*
  
  2018 Worldwide PAE Market Share: 
  ~25%

**SMT SOLUTIONS**

- **#1** in SMT Equipment Market
  
  *Since 2016*
  
  2018 Worldwide SMT Market Share: 
  ~23%

**MATERIALS**

- **#3** in Leadframe Market
  
  *Since 2018*
  
  2018 Worldwide Leadframe Market Share: 
  ~9%

Sources: Market share for Back-end Equipment is based on information on packaging and assembly equipment market by VLSI, leadframe market by SEMI, and SMT market by ASMPT SIPLACE Market Intelligence |
2019 Q3 Highlights
Double-digit Increases in Q3 Billing QoQ

<table>
<thead>
<tr>
<th>Segment</th>
<th>USD</th>
<th>QoQ</th>
</tr>
</thead>
<tbody>
<tr>
<td>Group</td>
<td>531m</td>
<td>+15.1%</td>
</tr>
<tr>
<td>Back-end Equipment Segment</td>
<td>233m</td>
<td>+12.8%</td>
</tr>
<tr>
<td>Materials Segment</td>
<td>63m</td>
<td>+9.8%</td>
</tr>
<tr>
<td>SMT Solutions Segment</td>
<td>235m</td>
<td>+19.0%</td>
</tr>
</tbody>
</table>

- **Group:** slightly below guidance due to deferral of revenue recognition of some tools to Q4
- **BE:** Advanced Packaging + CIS contributed to >50% Q3 BE revenue
- **SMT:** Continued to be driven by 5G infrastructure
- **Materials:** Leadframe market clearly on track to recovery
Q3 Billings – Business Segments

QoQ Growth:  
+12.8%

QoQ Growth:  
+19.0%

QoQ Growth:  
+9.8%

Back-End Equipment (USD'M)

SMT (USD'M)

Materials (USD'M)
Back-end & Materials Booking momentum continued in Q3

<table>
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<tr>
<th>Segment</th>
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<th>QoQ</th>
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</thead>
<tbody>
<tr>
<td>Group</td>
<td>514m</td>
<td>-14.6%</td>
</tr>
<tr>
<td>Back-end Equipment Segment</td>
<td>262m</td>
<td>+6.2%</td>
</tr>
<tr>
<td>Materials Segment</td>
<td>64m</td>
<td>+7.6%</td>
</tr>
<tr>
<td>SMT Solutions Segment</td>
<td>188m</td>
<td>-36.5%</td>
</tr>
</tbody>
</table>

- **BE:** Strong bookings led by CIS and China

- **Materials:** 3 quarters consecutive QoQ bookings growth – a clear sign of market recovery

- **SMT:** Q3 bookings ▼36.5% vs. high booking level in Q2

- Customers remain cautious in view of macro uncertainties
Q3 Bookings – Business Segments

QoQ Growth: +6.2%

QoQ Growth: -36.5%

QoQ Growth: +7.6%
**Significant improvement in PBT & Net Profit QoQ**

<table>
<thead>
<tr>
<th></th>
<th>Gross Margin</th>
<th>QoQ</th>
</tr>
</thead>
<tbody>
<tr>
<td><strong>Group</strong></td>
<td>34.7%</td>
<td>-100 bps</td>
</tr>
<tr>
<td><strong>Back-end Equipment Segment</strong></td>
<td>43.4%</td>
<td>+267 bps</td>
</tr>
<tr>
<td><strong>Materials Segment</strong></td>
<td>10.3%</td>
<td>-111 bps</td>
</tr>
<tr>
<td><strong>SMT Solutions Segment</strong></td>
<td>32.7%</td>
<td>-486 bps</td>
</tr>
<tr>
<td><strong>PBT</strong></td>
<td>HKD 345m</td>
<td>+85.6%</td>
</tr>
<tr>
<td><strong>Net Profit</strong></td>
<td>HKD 222m</td>
<td>+217.4%</td>
</tr>
</tbody>
</table>

- **Back-end:** GM ▲ 267 bps QoQ due to favorable product mix
- **SMT:** GM ▼ 486 bps due to sustained effort in penetrating Asian customer base with typically a lower GM
QoQ Bookings Growth: +6.2%

Key Highlights:

Back-end Equipment Segment

- Advanced Packaging and CIS together contributed to more than 50% of BE revenue in Q3
- Significant increase in orders contributed by China
- Demand for die and wire bonders showed signs of stabilization
- Segment profit ▲168.9% QoQ
- Cost reduction initiatives taking effect – YoY ▼10 bps in GM despite YoY ▼23.2% in Billings
Key Highlights:

SMT Segment

- Excellent performance extended to Q3 with Billings ↑19% QoQ
- Orders continued to be driven by 5G infrastructure, though offset by weaker Automotive market
- 9M Billing ▼ only 8% YoY despite challenging year
Key Highlights:

Materials Segment

- Lead frame market clearly on track to market recovery with consecutive 3 quarters Bookings growth
- Double digit YoY ▲17.9% Bookings growth for Materials
R&D Commitment Makes Us a Preferred Partner of Choice

9 months 2019 R&D expenditure

- US$ 161 million
- 12.5% of Equipment Sales

USD1,584 million invested in R&D

Q 3 HIGHLIGHTS

- Package Interconnection
- Optics precision engineering
- Vibration control
- Laser dicing & grooving
- SMT
An Extensive Customer Base

No single customer accounted for more than 10% of Group revenue

Top 5 customers accounted for 18% of Group’s Q3 2019 revenue

Top 20 customers include:
- World’s leading IDMs
- Tier 1 OSATs, major OSATs in China
- Key LED players
- Major camera module makers
- Top EMS providers
- Leading automotive component suppliers

Among Top 20 customers of Group:
- 6 from SMT Solutions segment
- 4 from both Back-End Equipment & SMT Solutions segment

China Leads Market Recovery
Endless Opportunities for ASMPT in the Digital World
Q3 2019 Revenue Drivers

Advanced Packaging

CMOS Imaging Sensor

5G

China Market
Data-Centric Era will spur Semiconductor Demand

- **Collect**
  - Camera, 3D Sensing, Industry IoT, Sensor, LIDAR

- **Transmit**
  - 5G, WiFi, LiFi

- **Store**
  - Big Data Centre, Cloud Computing, Memory

- **Analyse**
  - AI, TPU, Data Analytics, HPC

- **Visualise**
  - AR, VR, Micro LED, Mini LED

**ASMPT’s Enabling Solutions**

- CMOS Imaging Sensors
- Active Alignment
- Precision Die Attach
- Silicon Photonics
- RF Filters
- Wire Bonding
- SAW Filters
- BAW Filters
- SMT Solutions
- PVD
- Silicon Photonics
- TCB
- Wire Bonding
- PLFO
- Laser Dicing
- WLFO
- PLFO
- Pick & Place
- Laser Grooving
- TCB
- PVD/ECD
- Precision Die Attach
- Heterogeneous Integration
- High Precision Die Attach
- Mini/Micro LED Displays
Data Traffic To Continue ‘Exploding In Waves’ Over The Next Years

Global Data Traffic Facts (in Zettabytes)

Smartphone Innovations
Continue to Drive CIS Business

Under-Screen Camera (USC)
(Super-thin, thread-less lens)

Multi-Camera Combo, Folded optics
(WFOV -> 50x Super Zoom)

Super High Resolution
(24MP -> 48MP -> 64MP -> 100MP)

Biometrics
3D sensing, Under-Display FPS
Even more broad-based applications driving

Multi-year CIS growth

Source: ICinsights
The Role Of The Camera In The Data Era Redefined

Today
- Videos
- Still Images
- Social Media Content

Future
- Industrial Inspection with Drones
- AR/VR
- Artificial Intelligence
- Security: Features Recognition
- Autonomous Vehicles

Source: Youtube, Facebook, Instagram, IT World Canada, Nvidia, Precision Security Australia, Cramer.com, Weibo, Netflix, Youku
Advanced Packaging: The Game Changer in Semiconductor Revolution

Advanced Packaging Approaches

- SI TSV INTERPOSER
- EMBEDDED BRIDGE
- HIFO
- FIREBIRD TCB FLI
- NEXX PVD | ECD Bumping, TSV & RDL
- LASER 1205 Laser Separation Wafer Dicing and Grooving
- SIPLACE CA Die Attach & SMT Feeders

Advanced Packaging Technology Enabler

- HBM / Memory
- X-PU
- 2.5D Silicon Interposer
- HDI Substrate with Embedded Technology
- Integrated Passive Device, IPD integration

End Applications:

- AUTOMOTIVE Sensors, Camera, Body Electronics, Safety Systems, Infotainment
- DATACENTERS for HPC, Machine Learning
- IoT ERA Smart Wearables & Smart Machines (Factories)
- GPU for VR/AR & AI

Applications

- SI TSV INTERPOSER
- Embedded Bridge
- HIFO
- FIREBIRD TCB FLI
Growth of Packaging Market Mainly Driven by Advanced Packaging

Global Packaging Market (Billion $)

- 2014: $53 B
- 2023: $84 B
- Growth of ~2X

A.I. Share within Semi Industry Expected to Grow to >$100B in the Next Decade

- Deep learning
- Language processing
- Robots
- Vision

Source: YOLE Development, PwC Strategy & analysis, IC Insights, JP Morgan
5G Will Transform the World Beyond Our Imagination

Infrastructure

2019-2025: 25-30mil New 5G Base Stations
Source: Topology Research

Terminal

Big Data Cloud Servers

Mobile

Smart Consumer

Automotive

“Power” Up All Industries

50 MEMS & Sensors per car
Source: Bosch, 2019

ASMPT Solutions:

5G Will Transform the World Beyond Our Imagination

Power Solutions

IC & Discrete Solutions

Image Sensor Solutions

Wafer Separation

Photonics Solutions

SMT Solutions

Advanced Packaging

Source: Topology Research

2019-2025: 25-30mil New 5G Base Stations
Future Growth Drivers for OPTO Business

**MiniLED**
Medium to Large RGB / BLU Display
~ 66.1%
Market Size CAGR (2019 – 2027)

**MicroLED**
Small Gadget & Transparent Display
~ 139.5%
Market Size CAGR (2019 – 2027)

Source: Yanoresearch, Apr 2019
Booming Applications
In Photonics Market

Si Photonics-based Transceivers
Revenue CAGR (2018 – 2024)
~ 44.5 %
Source: Yole, Apr 2019

Data Center Interconnects
Telecommunication
LIDAR & Sensors

Defence & Aerospace
Intra-car Interconnects
Industrial Communication
Medical
How will ‘Smart Cars’ Drive ASMPT’s Growth?

5G to Cloud Connectivity
Vehicle-to-X (Vehicle, Infrastructure, Network, Devices) communications
Enable “V2X” communications

Sensors
Image, LIDAR, Radar
The eyes and ears to gather information from the Road

Power Management
Battery Technology for thermal management
Thermal management (e.g. Ag Sintering) will play important role

Entertainment Platform
Television, Mobile devices, VR/AR, Gaming, etc.
Frees up driver’s attention on road for entertainment
Equipment Industry to Benefit from China Supply Chain Localisation

Semi Equipment Spending 2020F Growth

China: 24%
Rest of World: 8%

Source: SEMI July 2019, Equipment Market Data Subscription
Outlook

- On a full year basis: expect all 3 business segments to experience YoY revenue decline

- Q4 Billing
  - Group Billing: USD 460m to USD 510m (subject to actual timing for revenue recognition)
  - Materials: anticipate QoQ and YoY revenue growth
  - BE/SMT: anticipate QoQ and YoY revenue decline

- Q4 Group Booking
  - Expect double-digit QoQ decline

- Q4 Group Gross Margin
  - Anticipate to decrease slightly due to forecasted lower revenue
On Track to Recovery Amidst Macro Uncertainties

- Expect more revenue recognition for substantial orders for Advanced Packaging panel deposition tools
- Best-in-class packaging/assembly solutions for mini/micro LED well accepted by leading players
- CIS poised to benefit from multi cameras and innovation in camera differentiation features
- Positively optimistic re longer-term growth potential for
  - Advanced Packaging, CIS, 5G, IoT, automotive electrification, Si Photonics, mini/micro LED
- Market reach expanding beyond IDM, OSAT, and EMS
## Industry Growth Forecast (2019)

### Semiconductor Industry

<table>
<thead>
<tr>
<th>Source</th>
<th>Year</th>
<th>Forecast</th>
</tr>
</thead>
<tbody>
<tr>
<td>VLSI, Jun-19</td>
<td></td>
<td>-9.7%</td>
</tr>
<tr>
<td>IHS Markit, Jun-19</td>
<td></td>
<td>-12.5%</td>
</tr>
<tr>
<td>IC Insights, May-19</td>
<td></td>
<td>-13.0%</td>
</tr>
<tr>
<td>Cowan LRA, May-19</td>
<td></td>
<td>-12.8%</td>
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<tr>
<td>WSTS, Jun-19</td>
<td></td>
<td>-12.1%</td>
</tr>
<tr>
<td>Gartner, Jun-19</td>
<td></td>
<td>-3.4%</td>
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</table>

### Forecast Global Assembly & Packaging Equipment Market

<table>
<thead>
<tr>
<th>Year</th>
<th>VLSI Assembly &amp; Packaging Equipment (Oct-19)</th>
<th>SEMI Assembly &amp; Packaging Equipment (Jul-19)</th>
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</thead>
<tbody>
<tr>
<td>2013</td>
<td>-22%</td>
<td>-26%</td>
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<tr>
<td>2014</td>
<td>22%</td>
<td>33%</td>
</tr>
<tr>
<td>2015</td>
<td>-16%</td>
<td>-18%</td>
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<tr>
<td>2016</td>
<td>13%</td>
<td>20%</td>
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<tr>
<td>2017</td>
<td>26%</td>
<td>26%</td>
</tr>
<tr>
<td>2018</td>
<td>-3%</td>
<td>1.9%</td>
</tr>
<tr>
<td>2019F</td>
<td>-20%</td>
<td>-23%</td>
</tr>
</tbody>
</table>
# Recent Awards & Recognition

## Latest

### 10 Best Chip Making Equipment Suppliers of 2019

<table>
<thead>
<tr>
<th>Rank</th>
<th>Segment</th>
<th>Company</th>
<th>Rating</th>
<th>Stars</th>
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</thead>
<tbody>
<tr>
<td>1</td>
<td>LARGE</td>
<td>TERADYNE</td>
<td>9.44</td>
<td>★★★★★</td>
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<tr>
<td>2</td>
<td>LARGE</td>
<td>ADVANTEST</td>
<td>9.23</td>
<td>★★★★★</td>
</tr>
<tr>
<td>3</td>
<td>LARGE</td>
<td>ASML</td>
<td>9.18</td>
<td>★★★★★</td>
</tr>
<tr>
<td>4</td>
<td>LARGE</td>
<td>ASM Pacific Technology</td>
<td>8.79</td>
<td>★★★★☆</td>
</tr>
<tr>
<td>5</td>
<td>LARGE</td>
<td>KLA</td>
<td>8.03</td>
<td>★★★★☆</td>
</tr>
<tr>
<td>6</td>
<td>LARGE</td>
<td>TEL</td>
<td>7.03</td>
<td>★★★★☆</td>
</tr>
<tr>
<td>7</td>
<td>LARGE</td>
<td>KE</td>
<td>7.75</td>
<td>★★★★☆</td>
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<tr>
<td>8</td>
<td>LARGE</td>
<td>Lam</td>
<td>7.61</td>
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<tr>
<td>9</td>
<td>LARGE</td>
<td>Applied Materials</td>
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<td>★★★★☆</td>
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<tr>
<td>10</td>
<td>LARGE</td>
<td>Hitachi HighTech</td>
<td>7.29</td>
<td>★★★★☆</td>
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<tr>
<td>1</td>
<td>FOCUSED</td>
<td>Plasma-Therm</td>
<td>9.39</td>
<td>★★★★★</td>
</tr>
<tr>
<td>2</td>
<td>FOCUSED</td>
<td>AMEC</td>
<td>9.01</td>
<td>★★★★★</td>
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<tr>
<td>3</td>
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<td>FormFactor</td>
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<td>★★★★★</td>
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<tr>
<td>4</td>
<td>FOCUSED</td>
<td>EV Group</td>
<td>8.51</td>
<td>★★★★★</td>
</tr>
<tr>
<td>5</td>
<td>FOCUSED</td>
<td>SPTS</td>
<td>7.46</td>
<td>★★★☆☆</td>
</tr>
<tr>
<td>6</td>
<td>FOCUSED</td>
<td>Cohu</td>
<td>7.09</td>
<td>★★★☆☆</td>
</tr>
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</table>

### What The Best Suppliers of 2019 Are Best At

- **ADVANTEST**
  - Partnering
  - Technical Leadership

- **AMEC**
  - Partnering
  - Commitment

- **ASM Pacific Technology**
  - Partnering
  - Trust in Supplier

- **ASML**
  - Technical Leadership
  - Partnering

- **Cohu**
  - Trust in Supplier

- **EVL**
  - Field Engineering Support
  - Technical Leadership

- **Hitachi HighTech**
  - Uptime
  - Product Performance

- **Japan Electronic Materials**
  - Product Performance
  - Support After Sales

- **KE**
  - Field Engineering Support
  - Recommended Supplier

- **KLA**
  - Technical Leadership
  - Application Support

- **Lam Research**
  - Partnering
  - Support After Sales

- **NDC**
  - Commitment
  - Support After Sales

- **Plasma-Therm**
  - Partnering
  - Trust in Supplier

- **SPTS**
  - Recommended Supplier
  - Field Engineering Support

- **TEL Tokyo**
  - Technical Leadership
  - Uptime

- **Technoprobe**
  - Commitment
  - Partnering and Recommended Supplier
2019 Q3
Financial Highlights
### Q3 Group Bookings

#### QoQ Growth:
-14.6%

<table>
<thead>
<tr>
<th></th>
<th>USD</th>
<th>YoY</th>
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<td>-36.5%</td>
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**Quarterly Group Bookings (USD'M)**

**Financial Review**
Q3 Group Billings

QoQ Growth: +15.1%

Quarterly Group Billings (USD'M)

<table>
<thead>
<tr>
<th></th>
<th>Q3 2019 Billings</th>
</tr>
</thead>
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</tbody>
</table>
### Q3 Group Financial Highlights

<table>
<thead>
<tr>
<th>Metric</th>
<th>Q3 2019</th>
<th>YoY</th>
<th>QoQ</th>
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</thead>
<tbody>
<tr>
<td>Bookings (USD)</td>
<td>514m</td>
<td>-16.9%</td>
<td>-14.6%</td>
</tr>
<tr>
<td>Revenue (USD)</td>
<td>531m</td>
<td>-19.5%</td>
<td>+15.1%</td>
</tr>
<tr>
<td>Gross Margin</td>
<td>34.7%</td>
<td>-307 bps</td>
<td>-100 bps</td>
</tr>
<tr>
<td>EBIT (HKD)</td>
<td>381m</td>
<td>-53.5%</td>
<td>+72.6%</td>
</tr>
<tr>
<td>Net Profit (HKD)</td>
<td>222m</td>
<td>-63.1%</td>
<td>+217.4%</td>
</tr>
<tr>
<td>Net Profit Margin</td>
<td>5.3%</td>
<td>-631 bps</td>
<td>+341 bps</td>
</tr>
</tbody>
</table>
## Q3 Segment Results – Back-End Equipment Business

<table>
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<tr>
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<th>Q3 2019</th>
<th>YoY</th>
<th>QoQ</th>
</tr>
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</tr>
<tr>
<td>Gross Margin</td>
<td>43.4%</td>
<td>-10 bps</td>
<td>+267 bps</td>
</tr>
<tr>
<td>Segment Profit (HKD)</td>
<td>179m</td>
<td>-62.8%</td>
<td>+168.9%</td>
</tr>
<tr>
<td>Segment Profit Margin</td>
<td>9.8%</td>
<td>-1,047 bps</td>
<td>+570 bps</td>
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</tbody>
</table>
Q3 Segment Results – Materials Business

<table>
<thead>
<tr>
<th></th>
<th>Q3 2019</th>
<th>YoY %</th>
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<tbody>
<tr>
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<td>63m</td>
<td>-18.5%</td>
<td>+9.8%</td>
</tr>
<tr>
<td>Gross Margin</td>
<td>10.3%</td>
<td>-63 bps</td>
<td>-111 bps</td>
</tr>
<tr>
<td>Segment Profit (HKD)</td>
<td>18m</td>
<td>-30.6%</td>
<td>-7.7%</td>
</tr>
<tr>
<td>Segment Profit Margin</td>
<td>3.7%</td>
<td>-65 bps</td>
<td>-70 bps</td>
</tr>
</tbody>
</table>
## Q3 Segment Results – SMT Solutions Business

<table>
<thead>
<tr>
<th></th>
<th>Q3 2019</th>
<th>YoY</th>
<th>QoQ</th>
</tr>
</thead>
<tbody>
<tr>
<td>Bookings (USD)</td>
<td>188m</td>
<td>-37.5%</td>
<td>-36.5%</td>
</tr>
<tr>
<td>Billings (USD)</td>
<td>235m</td>
<td>-15.7%</td>
<td>+19.0%</td>
</tr>
<tr>
<td>Gross Margin</td>
<td>32.7%</td>
<td>-634 bps</td>
<td>-486 bps</td>
</tr>
<tr>
<td>Segment Profit (HKD)</td>
<td>226m</td>
<td>-48.1%</td>
<td>+8.4%</td>
</tr>
<tr>
<td>Segment Profit Margin</td>
<td>12.3%</td>
<td>-764 bps</td>
<td>-120 bps</td>
</tr>
</tbody>
</table>